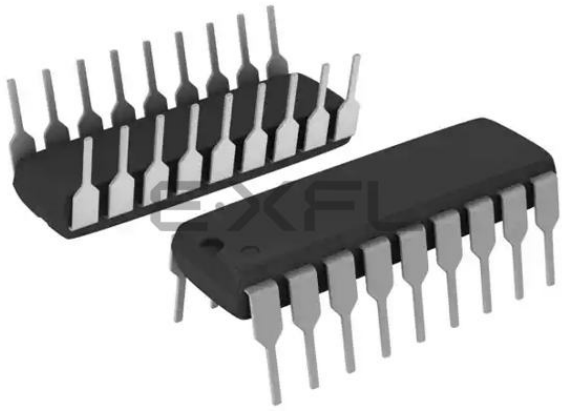

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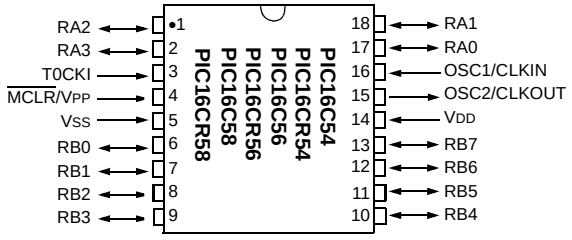
Applications of "Embedded - Microcontrollers"

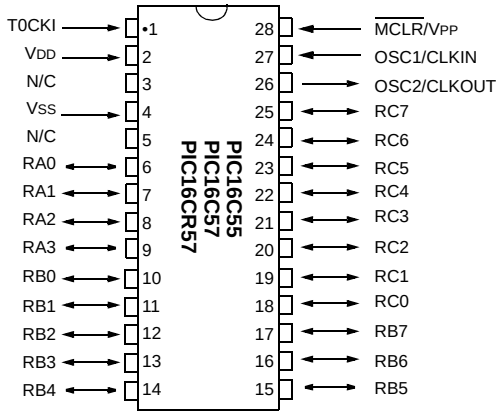
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	73 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc58b-04i-p

Pin Diagrams

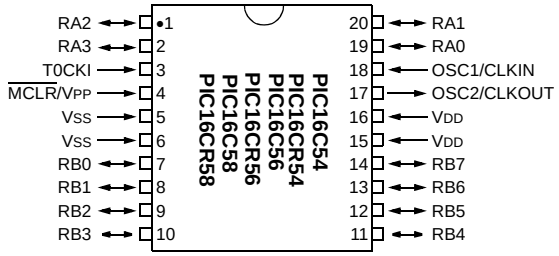
PDIP, SOIC, Windowed CERDIP



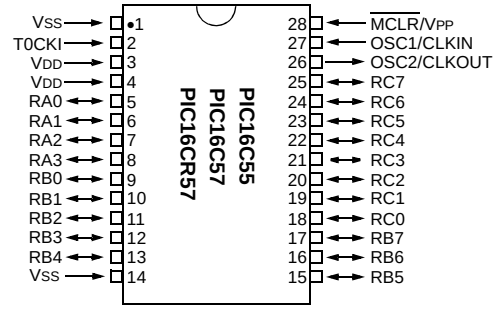
PDIP, SOIC, Windowed CERDIP



SSOP



SSOP



Device Differences

Device	Voltage Range	Oscillator Selection (Program)	Oscillator	Process Technology (Microns)	ROM Equivalent	$\overline{\text{MCLR}}$ Filter
PIC16C54	2.5-6.25	Factory	See **Note 1**	1.2	PIC16CR54A	No
PIC16C54A	2.0-6.25	User	See **Note 1**	0.9	—	No
PIC16C54C	2.5-5.5	User	See **Note 1**	0.7	PIC16CR54C	Yes
PIC16C55	2.5-6.25	Factory	See **Note 1**	1.7	—	No
PIC16C55A	2.5-5.5	User	See **Note 1**	0.7	—	Yes
PIC16C56	2.5-6.25	Factory	See **Note 1**	1.7	—	No
PIC16C56A	2.5-5.5	User	See **Note 1**	0.7	PIC16CR56A	Yes
PIC16C57	2.5-6.25	Factory	See **Note 1**	1.2	—	No
PIC16C57C	2.5-5.5	User	See **Note 1**	0.7	PIC16CR57C	Yes
PIC16C58B	2.5-5.5	User	See **Note 1**	0.7	PIC16CR58B	Yes
PIC16CR54A	2.5-6.25	Factory	See **Note 1**	1.2	N/A	Yes
PIC16CR54C	2.5-5.5	Factory	See **Note 1**	0.7	N/A	Yes
PIC16CR56A	2.5-5.5	Factory	See **Note 1**	0.7	N/A	Yes
PIC16CR57C	2.5-5.5	Factory	See **Note 1**	0.7	N/A	Yes
PIC16CR58B	2.5-5.5	Factory	See **Note 1**	0.7	N/A	Yes

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

Note: The table shown above shows the generic names of the PIC16C5X devices. For device varieties, please refer to Section 2.0.

5.0 RESET

PIC16C5X devices may be RESET in one of the following ways:

- Power-On Reset (POR)
- $\overline{MCLR}$ Reset (normal operation)
- $\overline{MCLR}$ Wake-up Reset (from SLEEP)
- WDT Reset (normal operation)
- WDT Wake-up Reset (from SLEEP)

Table 5-1 shows these RESET conditions for the PCL and STATUS registers.

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-On Reset (POR), $\overline{MCLR}$ or WDT Reset. A $\overline{MCLR}$ or WDT wake-up from SLEEP also results in a device RESET, and not a continuation of operation before SLEEP.

The $\overline{TO}$ and $\overline{PD}$ bits (STATUS <4:3>) are set or cleared depending on the different RESET conditions (Table 5-1). These bits may be used to determine the nature of the RESET.

Table 5-3 lists a full description of RESET states of all registers. Figure 5-1 shows a simplified block diagram of the On-chip Reset circuit.

TABLE 5-1: STATUS BITS AND THEIR SIGNIFICANCE

Condition	$\overline{TO}$	$\overline{PD}$
Power-On Reset	1	1
$\overline{MCLR}$ Reset (normal operation)	u	u
$\overline{MCLR}$ Wake-up (from SLEEP)	1	0
WDT Reset (normal operation)	0	1
WDT Wake-up (from SLEEP)	0	0

Legend: u = unchanged, x = unknown, – = unimplemented read as '0'.

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH RESET

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on $\overline{MCLR}$ and WDT Reset
03h	STATUS	PA2	PA1	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, q = see Table 5-1 for possible values.

8.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer (WDT), respectively (Section 9.2.1). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1`, `MOVWF 1`, `BSF 1,x`, etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a RESET, the prescaler contains all '0's.

8.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 8-1) must be executed when changing the prescaler assignment from Timer0 to the WDT.

EXAMPLE 8-1: CHANGING PRESCALER (TIMER0→WDT)

```
CLRWDT              ;Clear WDT
CLRF   TMR0         ;Clear TMR0 & Prescaler
MOVLW  B'00xx1111'  ;Last 3 instructions in
                     this example
OPTION              ;are required only if
                    ;desired
CLRWDT              ;PS<2:0> are 000 or
                    ;001
MOVLW  B'00xx1xxx'  ;Set Prescaler to
OPTION              ;desired WDT rate
```

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 8-2. This sequence must be used even if the WDT is disabled. A `CLRWDT` instruction should be executed before switching the prescaler.

EXAMPLE 8-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT                  ;Clear WDT and
                        ;prescaler
MOVLW   B'xxxx0xxx'     ;Select TMR0, new
                        ;prescale value and
                        ;clock source
OPTION
```


11.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

11.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

11.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16C5X-RCE	3.25	—	6.0	V	
		PIC16C5X-XTE	3.25	—	6.0	V	
		PIC16C5X-10E	4.5	—	5.5	V	
		PIC16C5X-HSE	4.5	—	5.5	V	
		PIC16C5X-LPE	2.5	—	6.0	V	
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current(2)**					
		PIC16C5X-RCE(3)	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-XTE	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-10E	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HSE	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HSE	—	9.0	20	mA	FOSC = 16 MHz, VDD = 5.5V
		PIC16C5X-LPE	—	19	55	μA	FOSC = 32 kHz, VDD = 3.25V, WDT disabled
D020	IPD	**Power-down Current(2)**	—	5.0	22	μA	VDD = 3.25V, WDT enabled
			—	0.8	18	μA	VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 **PIC16LCR54A-04I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16CR54A-04, 10, 20 **PIC16CR54A-04I, 10I, 20I** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LCR54A	2.0	—	6.25	V	
D001 D001A		PIC16CR54A	2.5 4.5	— —	6.25 5.5	V V	RC and XT modes HS mode
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	**Supply Current(2)**					
D005		PICLCR54A	— —	10 —	20 70	µA µA	Fosc = 32 kHz, VDD = 2.0V Fosc = 32 kHz, VDD = 6.0V
D005A		PIC16CR54A					**RC(3) and XT modes:**
			— — —	2.0 0.8 90	3.6 1.8 350	mA mA µA	FOSC = 4.0 MHz, VDD = 6.0V FOSC = 4.0 MHz, VDD = 3.0V FOSC = 200 kHz, VDD = 2.5V
							HS mode:
			— —	4.8 9.0	10 20	mA mA	FOSC = 10 MHz, VDD = 5.5V FOSC = 20 MHz, VDD = 5.5V

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

13.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

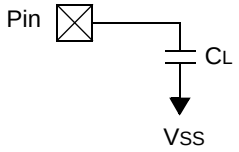
Lowercase letters (pp) and their meanings:

pp	
2 to	mc $\overline{\text{MCLR}}$
ck CLKOUT	osc oscillator
cy cycle time	os OSC1
drt device reset timer	t0 T0CKI
io I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S	
F Fall	P Period
H High	R Rise
I Invalid (Hi-impedance)	V Valid
L Low	Z Hi-impedance

FIGURE 13-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16CR54A



C_L = 50 pF for all pins and OSC2 for RC modes

0 -15 pF for OSC2 in XT, HS or LP modes when external clock is used to drive OSC1

15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial)
PIC16C54A-04I, 10I, 20I (Industrial)
PIC16LC54A-04 (Commercial)
PIC16LC54A-04I (Industrial)

PIC16LC54A-04 **PIC16LC54A-04I** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial
PIC16C54A-04, 10, 20 **PIC16C54A-04I, 10I, 20I** (Commercial, Industrial)	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial

Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
	IPD	**Power-down Current(2)**					
D006		PIC16LC5X	—	2.5	12	µA	VDD = 2.5V, WDT enabled, Commercial
			—	0.25	4.0	µA	VDD = 2.5V, WDT disabled, Commercial
			—	2.5	14	µA	VDD = 2.5V, WDT enabled, Industrial
			—	0.25	5.0	µA	VDD = 2.5V, WDT disabled, Industrial
D006A		PIC16C5X	—	4.0	12	µA	VDD = 3.0V, WDT enabled, Commercial
			—	0.25	4.0	µA	VDD = 3.0V, WDT disabled, Commercial
			—	5.0	14	µA	VDD = 3.0V, WDT enabled, Industrial
			—	0.3	5.0	µA	VDD = 3.0V, WDT disabled, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

15.4 DC Characteristics: PIC16C54A-04, 10, 20, PIC16LC54A-04, PIC16LV54A-02 (Commercial) PIC16C54A-04I, 10I, 20I, PIC16LC54A-04I, PIC16LV54A-02I (Industrial) PIC16C54A-04E, 10E, 20E, PIC16LC54A-04E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial-PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D030	VIL	**Input Low Voltage**					
		I/O ports	VSS	—	0.2 VDD	V	Pin at hi-impedance
		MCLR (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		T0CKI (Schmitt Trigger)	VSS	—	0.15 VDD	V	
		OSC1 (Schmitt Trigger)	VSS	—	0.15 VDD	V	RC mode only(3)
		OSC1	VSS	—	0.3 VDD		XT, HS and LP modes
D040	VIH	**Input High Voltage**					
		I/O ports	0.2 VDD + 1	—	VDD	V	For all VDD(4)
		I/O ports	2.0	—	VDD	V	4.0V < VDD ≤ 5.5V(4)
		MCLR (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		T0CKI (Schmitt Trigger)	0.85 VDD	—	VDD	V	
		OSC1 (Schmitt Trigger)	0.85 VDD	—	VDD	V	RC mode only(3)
		OSC1	0.7 VDD	—	VDD	V	XT, HS and LP modes
D050	VHYS	**Hysteresis of Schmitt Trigger inputs**	0.15 VDD*	—	—	V	
D060	IIL	**Input Leakage Current(1,2)**					**For VDD ≤ 5.5V:**
		I/O ports	-1.0	0.5	+1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
		MCLR	-5.0	—	+5.0	µA	VPIN = VSS +0.25V
		MCLR	—	0.5	+3.0	µA	VPIN = VDD
		T0CKI	-3.0	0.5	+3.0	µA	VSS ≤ VPIN ≤ VDD
		OSC1	-3.0	0.5	—	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	**Output Low Voltage**					
		I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
		OSC2/CLKOUT	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, RC mode only
	VOH	**Output High Voltage(2)**					
		I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V
		OSC2/CLKOUT	VDD - 0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, RC mode only

* These parameters are characterized but not tested.

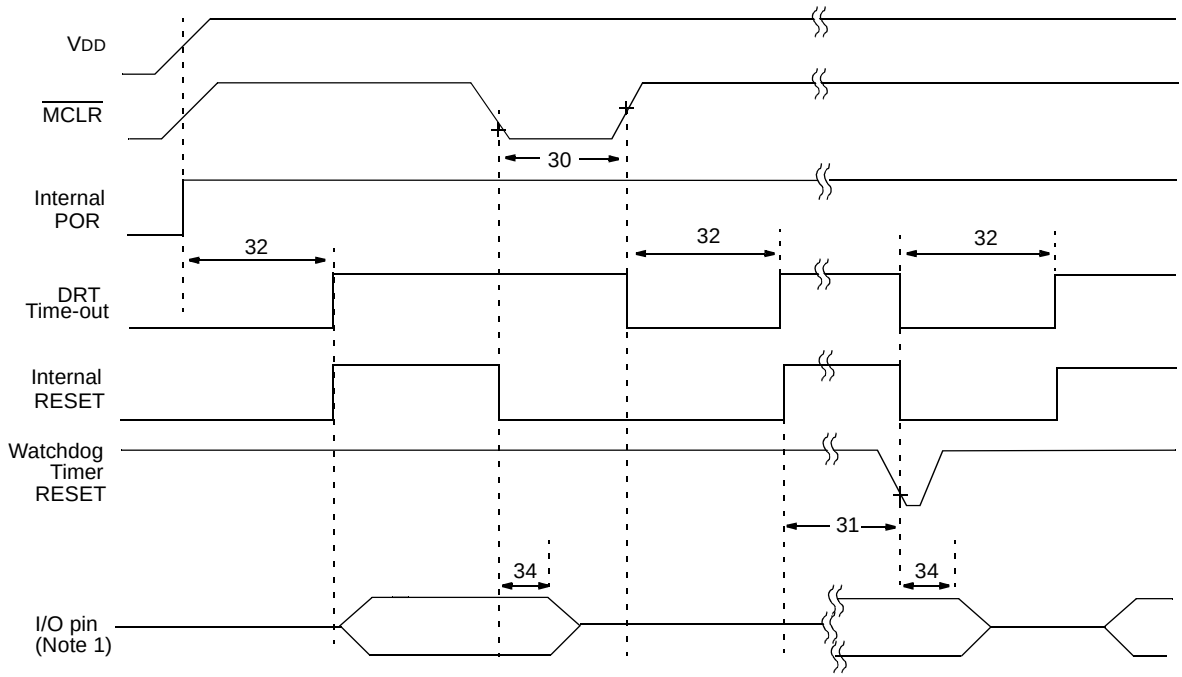
† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

FIGURE 15-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C54A



Note 1: Please refer to Figure 15-1 for load conditions.

TABLE 15-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C54A

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I –40°C ≤ TA ≤ +125°C for extended						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
30	TmcL	$\overline{MCLR}$ Pulse Width (low)	100* 1	— —	— —	ns µs	VDD = 5.0V VDD = 5.0V (PIC16LV54A only)
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from $\overline{MCLR}$ Low	— —	— —	100* 1µs	ns —	 (PIC16LV54A only)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

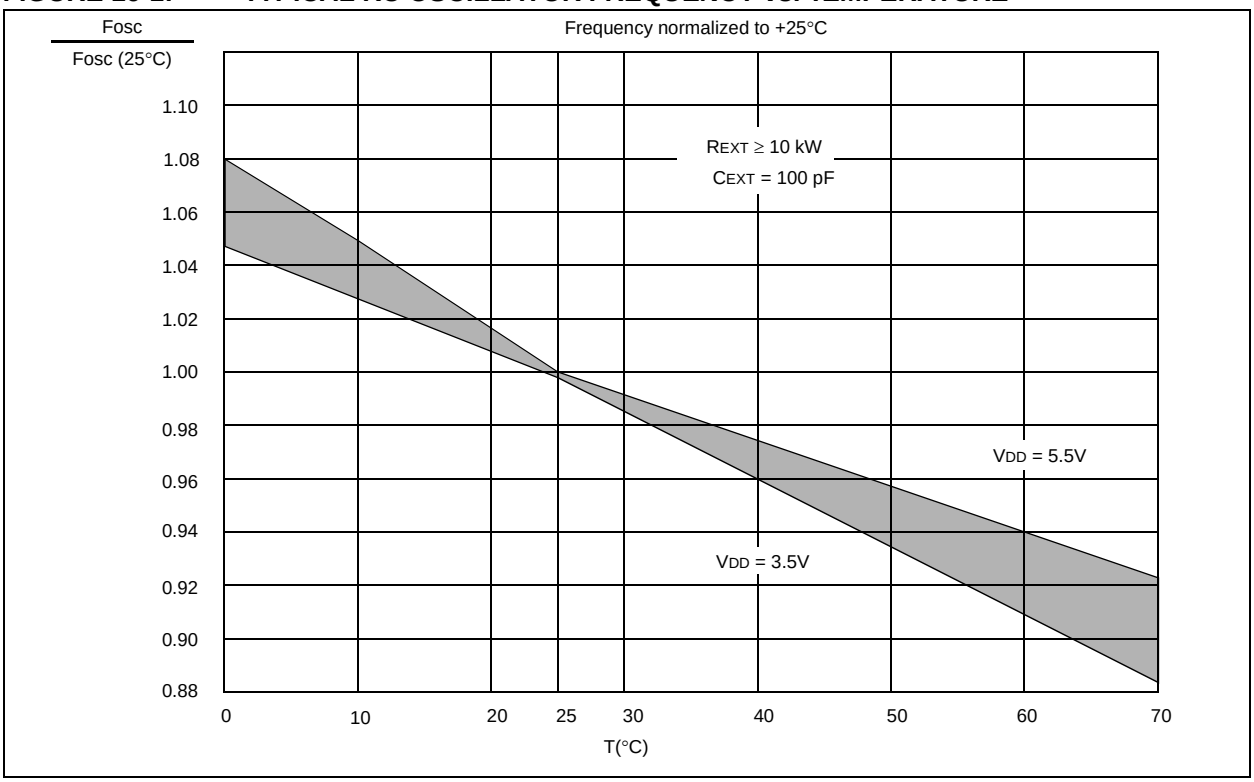


TABLE 16-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average Fosc @ 5 V, 25°C	
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.6 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C5X **PIC16CR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		PIC16LC5X	2.5 2.7 2.5	— — —	5.5 5.5 5.5	V V V	–40°C ≤ TA ≤ + 85°C, 16LCR5X –40°C ≤ TA ≤ 0°C, 16LC5X 0°C ≤ TA ≤ + 85°C 16LC5X
D001A		PIC16C5X	 3.0 4.5	 — —	 5.5 5.5	 V V	RC, XT, LP and HS mode from 0 - 10 MHz from 10 - 20 MHz
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C5X **PIC16CR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current(2,3)**					
D010		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	14	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	
			—	4.5	16	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	14	32	µA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	17	40	µA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
							FOSC = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

17.2 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04E, 20E (Extended) PIC16CR54C/CR56A/CR57C/CR58B-04E, 20E (Extended)

PIC16C54C/C55A/C56A/C57C/C58B-04E, 20E **PIC16CR54C/CR56A/CR57C/CR58B-04E, 20E** (Extended)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					RC, XT, LP, and HS mode
			3.0	—	5.5	V	from 0 - 10 MHz
			4.5	—	5.5	V	from 10 - 20 MHz
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD start voltage** to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD rise rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current(2)**					
		XT and RC(3) modes	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V
		HS mode	—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V
D020	IPD	**Power-down Current(2)**	—	0.3	17	µA	VDD = 3.0V, WDT disabled
			—	10	50*	µA	VDD = 4.5V, WDT disabled
			—	12	60*	µA	VDD = 5.5V, WDT disabled
			—	4.8	31*	µA	VDD = 3.0V, WDT enabled
			—	18	68*	µA	VDD = 4.5V, WDT enabled
			—	26	90*	µA	VDD = 5.5V, WDT enabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

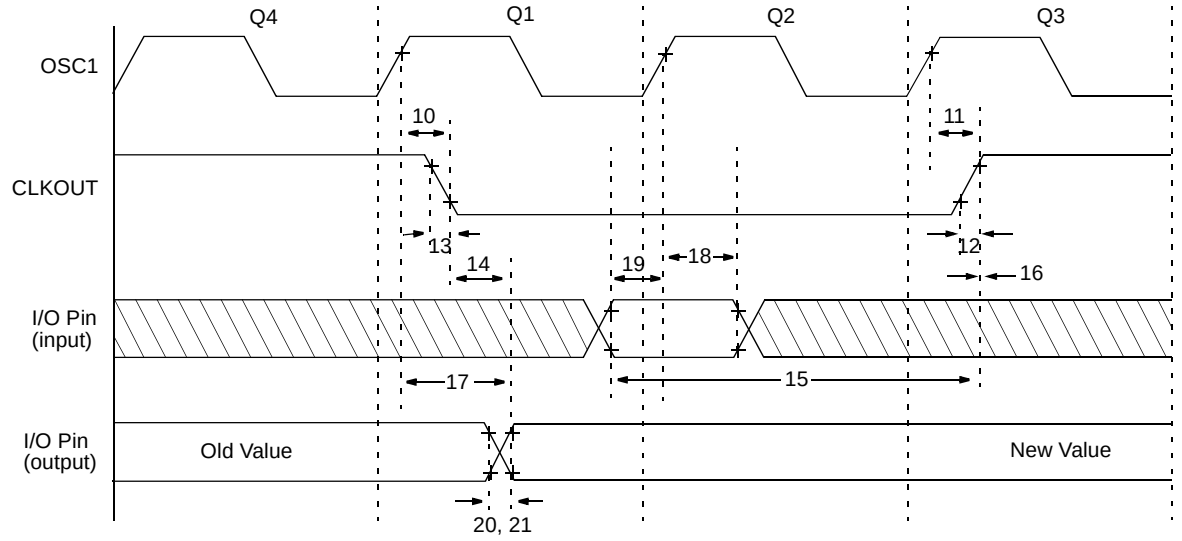
2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/ disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 17-7: CLKOUT AND I/O TIMING - PIC16C5X, PIC16CR5X



Note: Refer to Figure 17-5 for load conditions.

TABLE 17-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics	**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**
10	TosH2ckL	OSC1↑ to CLKOUT↓ **(1)**	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ **(1)**	—	15	30**	ns
12	TckR	CLKOUT rise time **(1)**	—	5.0	15**	ns
13	TckF	CLKOUT fall time **(1)**	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid **(1)**	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ **(1)**	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ **(1)**	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid **(2)**	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time **(2)**	—	10	25**	ns
21	TioF	Port output fall time **(2)**	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Refer to Figure 17-5 for load conditions.

FIGURE 18-18: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 5 V

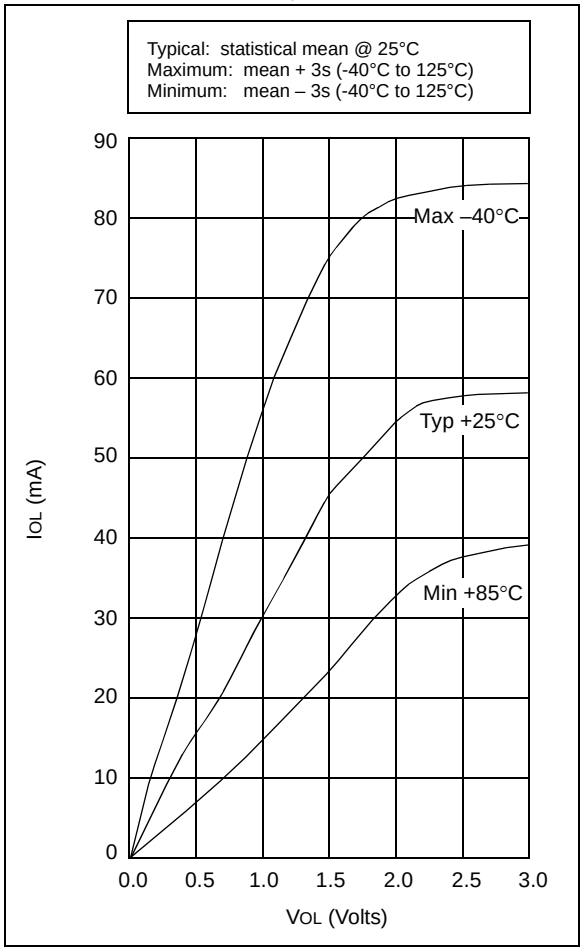


TABLE 18-2: INPUT CAPACITANCE

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
$\overline{MCLR}$	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

19.3 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T	
F Frequency	T Time

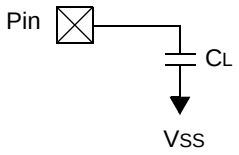
Lowercase letters (pp) and their meanings:

pp	
2 to	mc $\overline{\text{MCLR}}$
ck CLKOUT	osc oscillator
cy cycle time	os OSC1
drt device reset timer	t0 T0CKI
io I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S	
F Fall	P Period
H High	R Rise
I Invalid (Hi-impedance)	V Valid
L Low	Z Hi-impedance

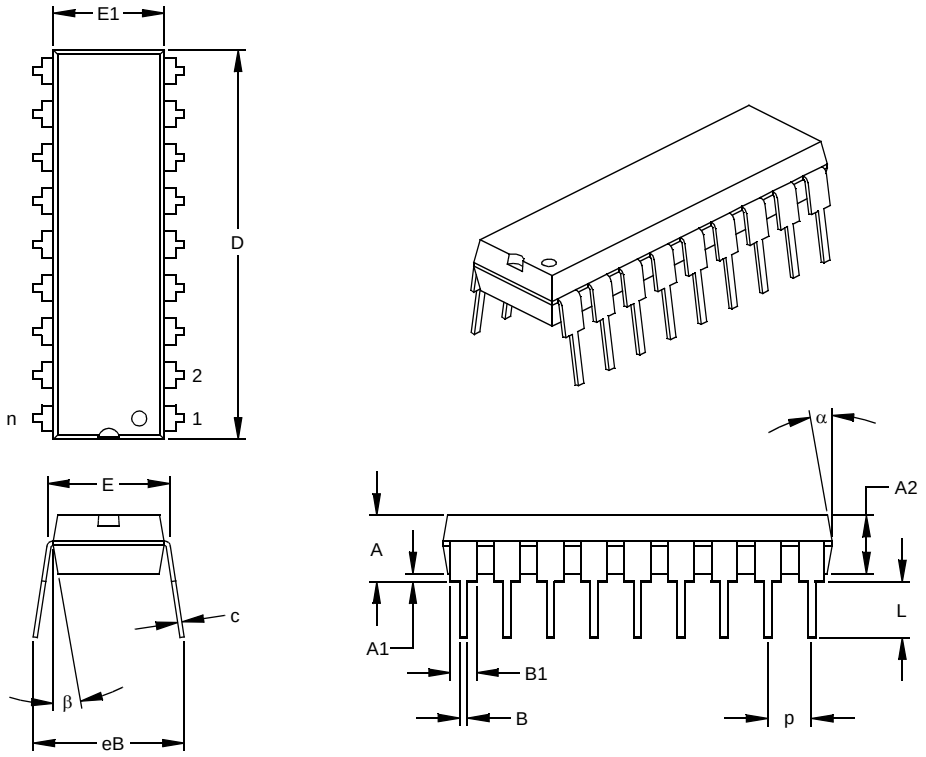
FIGURE 19-2: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54C/C55A/C56A/C57C/C58B-40



C_L = 50 pF for all pins except OSC2
0 pF for OSC2 in HS mode for operation between 20 MHz to 40 MHz

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



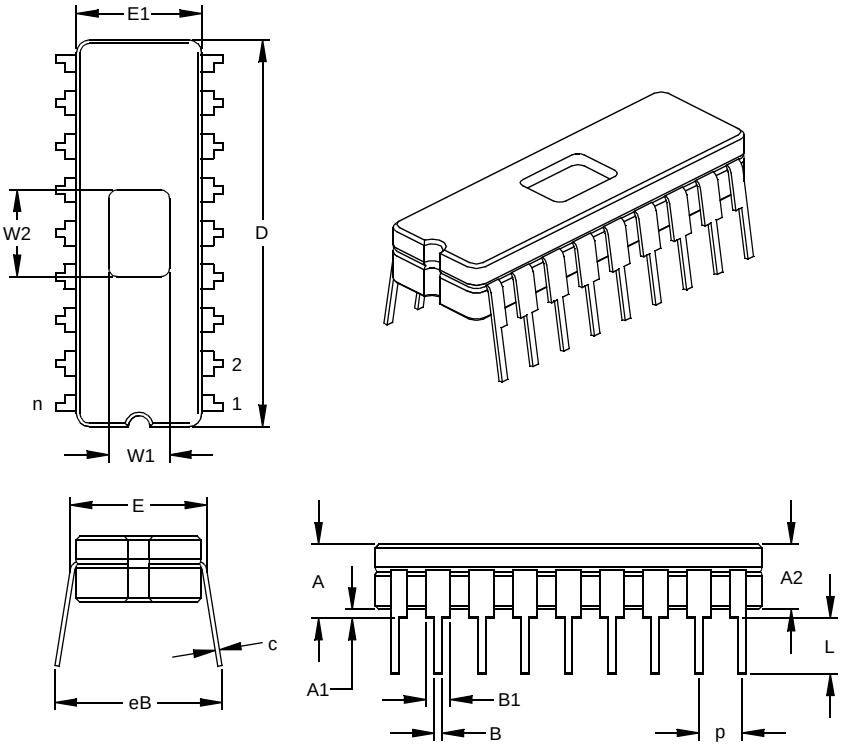
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

W

X

Z